



BOARD LEVEL COOLING – 3742

3742 is a square pin fin board level heat sink designed to cool BGA and FPGA devices. Representative image only.

ORDERING INFORMATION

Part Number	Device Type
374224B60023G	BGA, FPGA

HEAT SINK DETAILS

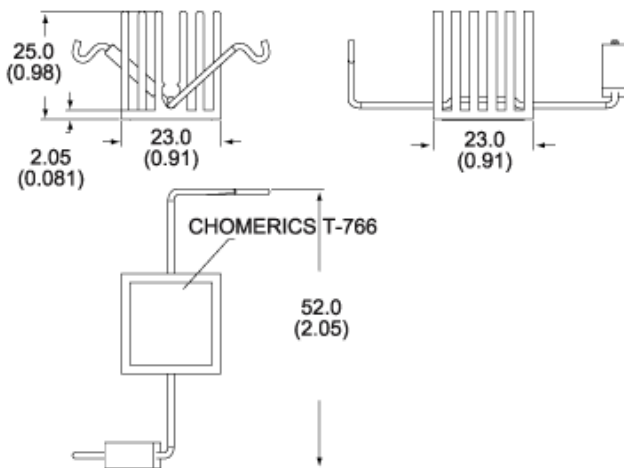
Property	Details
Material	Aluminum
Finish	Black Anodize
Device Attachment Options	Solder Anchor Clip
Thermal Interface Material	T766 Chomerics Phase Change for All Surfaces

Property	Details
Heat Sink Width (mm)	23.0
Heat Sink Length (mm)	23.0
Heat Sink Height (mm)	25.0
Heat Sink Mounting Direction	Horizontal, Vertical



MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)



Mounting Details:

